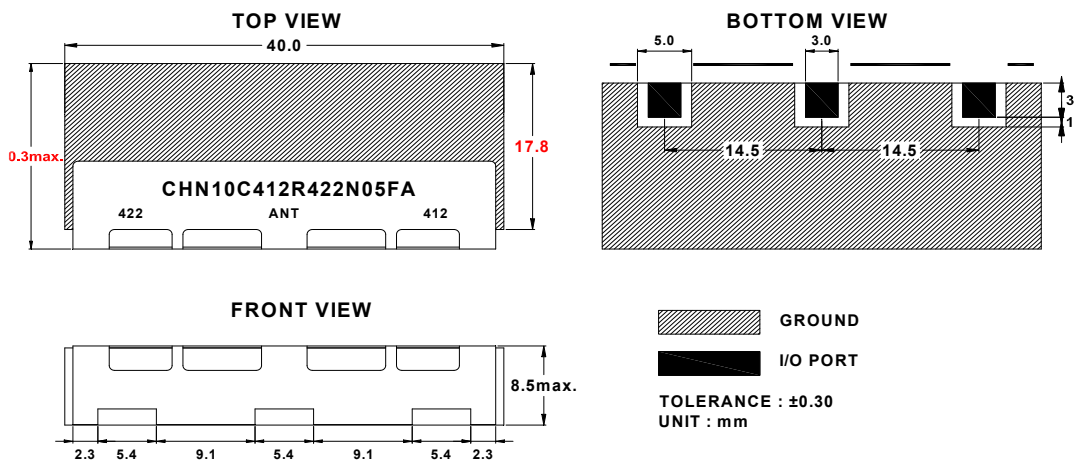


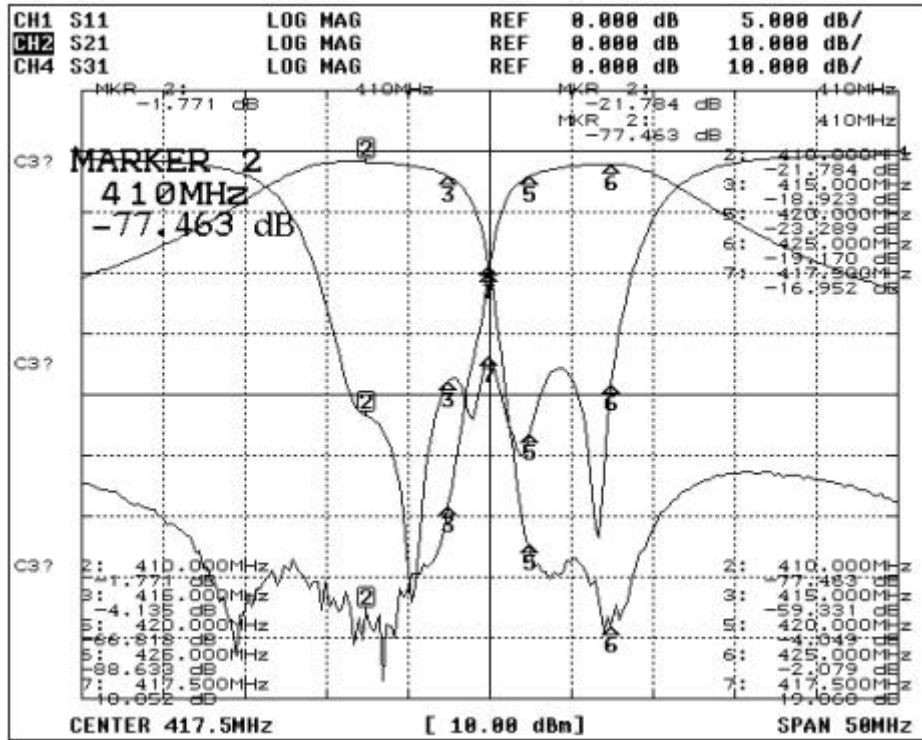
Electrical Specification

ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	412.5	422.5	MHz
Bandwidth [BW]	fo ±2.5 [410.0 ~ 415.0]	fo ±2.5 [420.0 ~ 425.0]	MHz
Insertion Loss in BW	4.5	4.5	dB max
Ripple in BW	2.5	2.5	dB max
Return Loss in BW	15.0	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	60.0 dB min. @ [420.0 ~ 425.0]	60.0 dB min. @ [410.0 ~ 415.0]	MHz
	18.0 dB min. @ [417.50 ~]	18.0 dB min. @ [417.50 ~]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
Isolations	dB min. @ [~]		MHz
	dB min. @ [~]		MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

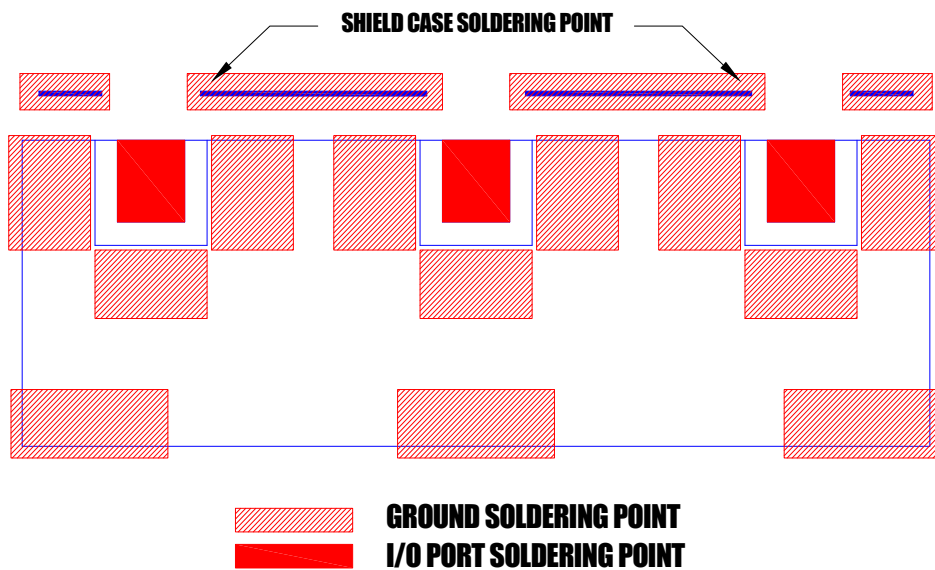
Mechanical Specification



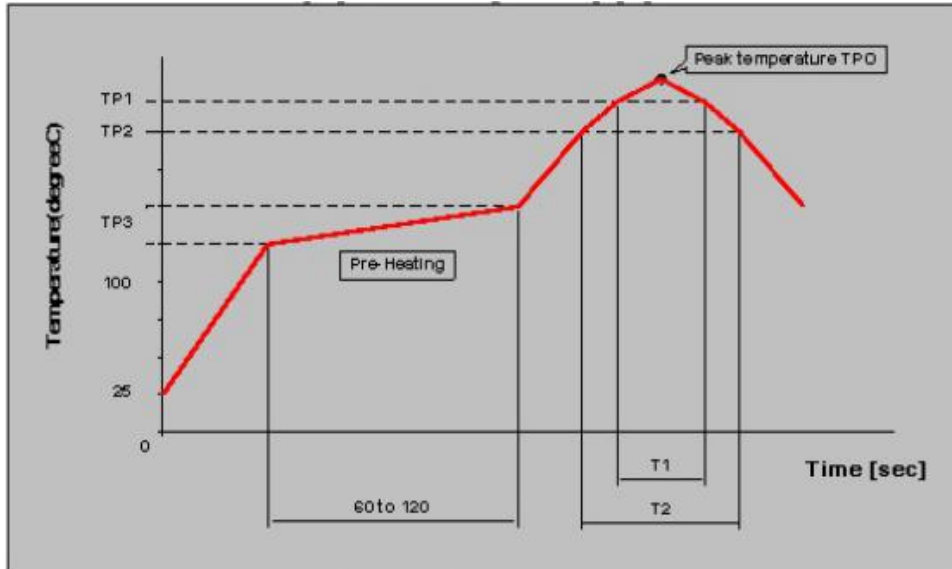
Plot Data



Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180